



FDD6688/FDU6688

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## 30V N-Channel PowerTrench<sup>®</sup> MOSFET

### General Description

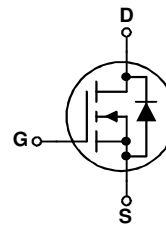
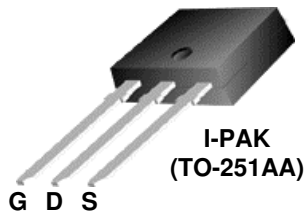
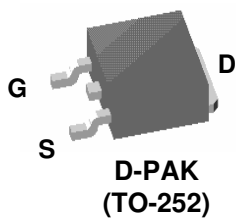
This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, low  $R_{DS(ON)}$  and fast switching speed.

### Applications

- DC/DC converter
- Motor Drives

### Features

- 84 A, 30 V.  $R_{DS(ON)} = 5\text{ m}\Omega @ V_{GS} = 10\text{ V}$   
 $R_{DS(ON)} = 6\text{ m}\Omega @ V_{GS} = 4.5\text{ V}$
- Low gate charge
- Fast switching
- High performance trench technology for extremely low  $R_{DS(ON)}$



### Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Ratings	Units
$V_{DSS}$	Drain-Source Voltage	30	V
$V_{GSS}$	Gate-Source Voltage	$\pm 20$	
$I_D$	Drain Current – Continuous (Note 3)	84	A
	– Pulsed (Note 1a)	100	
$P_D$	Power Dissipation for Single Operation (Note 1)	83	W
	(Note 1a)	3.8	
	(Note 1b)	1.6	
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	$-55$ to $+175$	$^\circ\text{C}$

### Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction-to-Case (Note 1)	1.8	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1a)	40	
	(Note 1b)	96	

### Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape width	Quantity
FDD6688	FDD6688	D-PAK (TO-252)	13"	16mm	2500 units
FDU6688	FDU6688	I-PAK (TO-251)	Tube	N/A	75

## Electrical Characteristics

$T_A = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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### Drain-Source Avalanche Ratings (Note 2)

$W_{DSS}$	Drain-Source Avalanche Energy	Single Pulse, $V_{DD} = 15\text{ V}$ , $I_D = 21\text{ A}$			370	mJ
$I_{AR}$	Drain-Source Avalanche Current				21	A

### Off Characteristics

$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}$ , $I_D = 250\ \mu\text{A}$	30			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250\ \mu\text{A}$ , Referenced to $25^\circ\text{C}$		24		mV/ $^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 24\text{ V}$ , $V_{GS} = 0\text{ V}$			1	$\mu\text{A}$
$I_{GSS}$	Gate-Body Leakage	$V_{GS} = \pm 20\text{ V}$ , $V_{DS} = 0\text{ V}$			$\pm 100$	nA

### On Characteristics (Note 2)

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$ , $I_D = 250\ \mu\text{A}$	1	1.8	3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	$I_D = 250\ \mu\text{A}$ , Referenced to $25^\circ\text{C}$		-5		mV/ $^\circ\text{C}$
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 10\text{ V}$ , $I_D = 18\text{ A}$ $V_{GS} = 4.5\text{ V}$ , $I_D = 16.5\text{ A}$ $V_{GS} = 10\text{ V}$ , $I_D = 18\text{ A}$ , $T_J = 125^\circ\text{C}$		4 5 6	5 6 10	m $\Omega$
$I_{D(on)}$	On-State Drain Current	$V_{GS} = 10\text{ V}$ , $V_{DS} = 5\text{ V}$	50			A
$g_{FS}$	Forward Transconductance	$V_{DS} = 5\text{ V}$ , $I_D = 18\text{ A}$		88		S

### Dynamic Characteristics

$C_{iss}$	Input Capacitance	$V_{DS} = 15\text{ V}$ , $V_{GS} = 0\text{ V}$ ,		3845		pF
$C_{oss}$	Output Capacitance	$f = 1.0\text{ MHz}$		930		pF
$C_{rss}$	Reverse Transfer Capacitance			368		pF
$R_G$	Gate Resistance	$V_{GS} = 15\text{ mV}$ , $f = 1.0\text{ MHz}$		1.2		$\Omega$

### Switching Characteristics (Note 2)

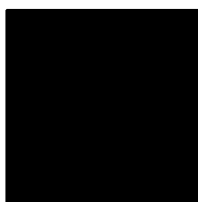
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 15\text{ V}$ , $I_D = 1\text{ A}$ ,		15	27	ns
$t_r$	Turn-On Rise Time	$V_{GS} = 10\text{ V}$ , $R_{GEN} = 6\ \Omega$		13	23	ns
$t_{d(off)}$	Turn-Off Delay Time			62	99	ns
$t_f$	Turn-Off Fall Time			36	58	ns
$Q_g$	Total Gate Charge	$V_{DS} = 15\text{ V}$ , $I_D = 18\text{ A}$ ,		37	56	nC
$Q_{gs}$	Gate-Source Charge	$V_{GS} = 5\text{ V}$		10		nC
$Q_{gd}$	Gate-Drain Charge			14		nC

**Electrical Characteristics** (continued) T<sub>A</sub> = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
<b>Drain–Source Diode Characteristics and Maximum Ratings</b>						
V <sub>SD</sub>	Drain–Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 3.2 A (Note 2)		0.7	1.2	V
t <sub>rr</sub>	Diode Reverse Recovery Time	I <sub>F</sub> = 18 A, d <sub>iF</sub> /d <sub>t</sub> = 100 A/μs		39		nS
Q <sub>rr</sub>	Diode Reverse Recovery Charge			31		nC

**Notes:**

- R<sub>θJA</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R<sub>θJC</sub> is guaranteed by design while R<sub>θCA</sub> is determined by the user's board design.



a) R<sub>θJA</sub> = 40°C/W when mounted on a 1 in<sup>2</sup> pad of 2 oz copper



b) R<sub>θJA</sub> = 96°C/W when mounted on a minimum pad.

Scale 1 : 1 on letter size paper

- Pulse Test: Pulse Width < 300μs, Duty Cycle < 2.0%

- Maximum current is calculated as: 
$$\sqrt{\frac{P_D}{R_{DS(ON)}}}$$

where P<sub>D</sub> is maximum power dissipation at T<sub>C</sub> = 25°C and R<sub>DS(on)</sub> is at T<sub>J(max)</sub> and V<sub>GS</sub> = 10V. Package current limitation is 21A

## Typical Characteristics

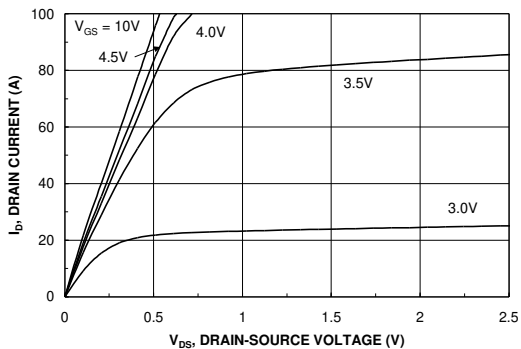


Figure 1. On-Region Characteristics.

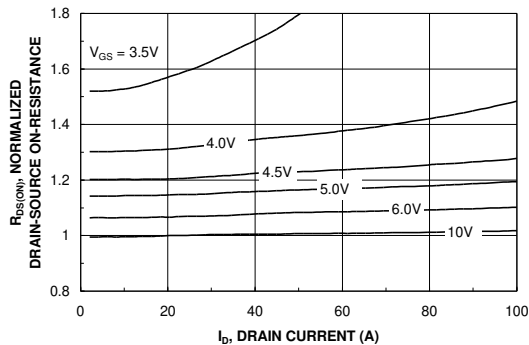


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

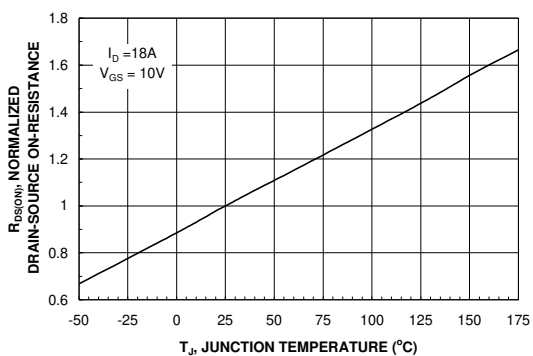


Figure 3. On-Resistance Variation with Temperature.

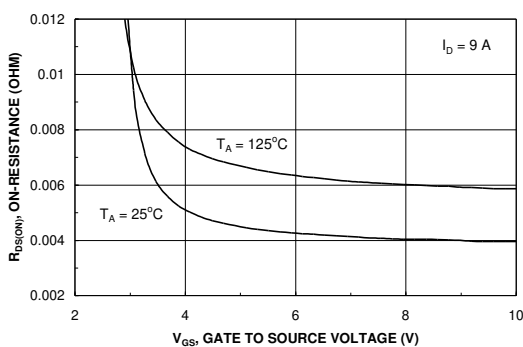


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

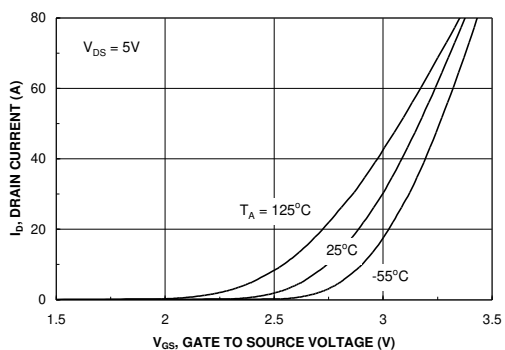


Figure 5. Transfer Characteristics

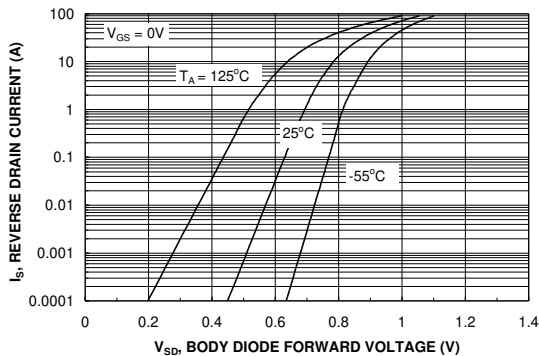


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature

## Typical Characteristics

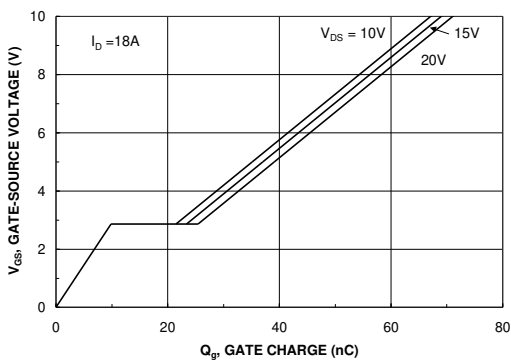


Figure 7. Gate Charge Characteristics

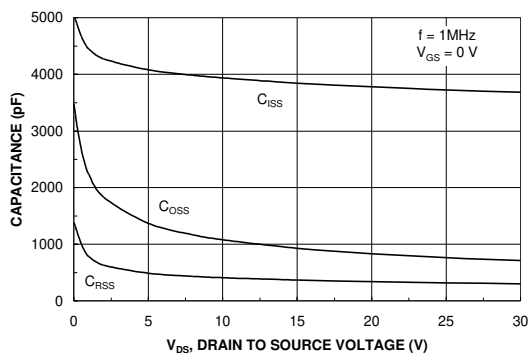


Figure 8. Capacitance Characteristics

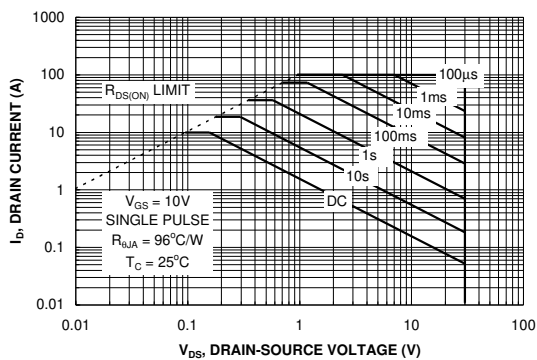


Figure 9. Maximum Safe Operating Area

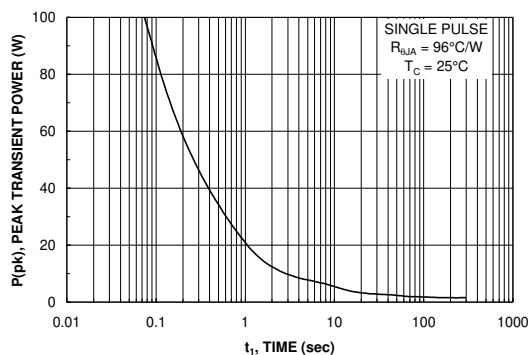


Figure 10. Single Pulse Maximum Power Dissipation

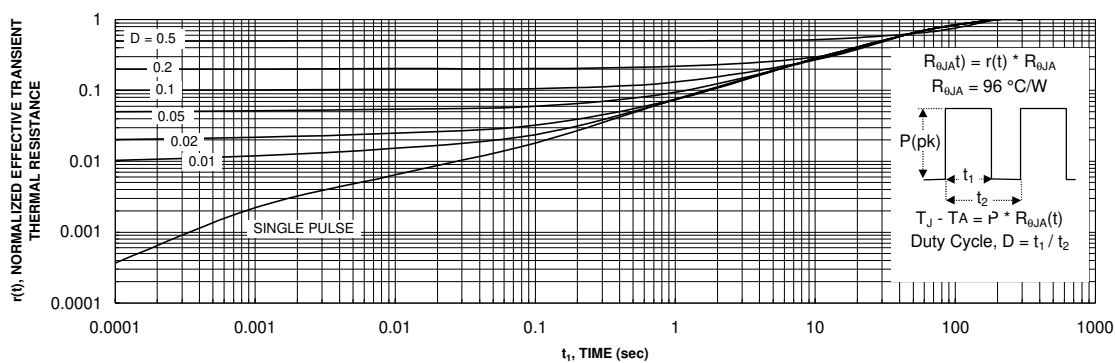
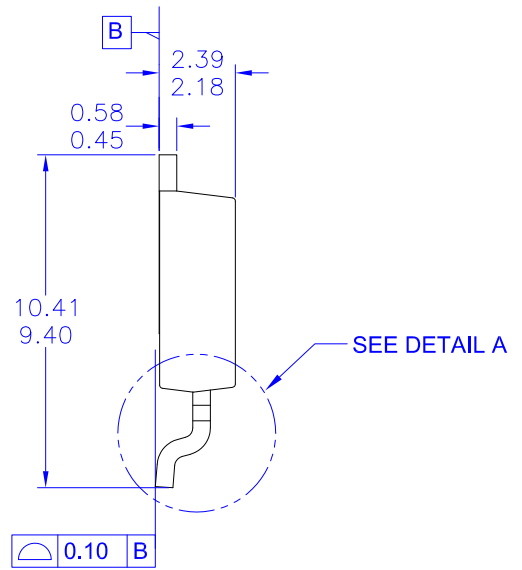
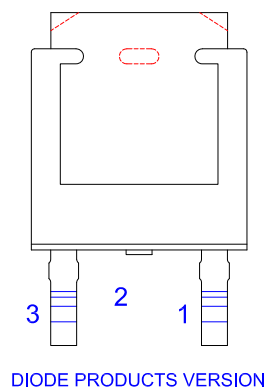
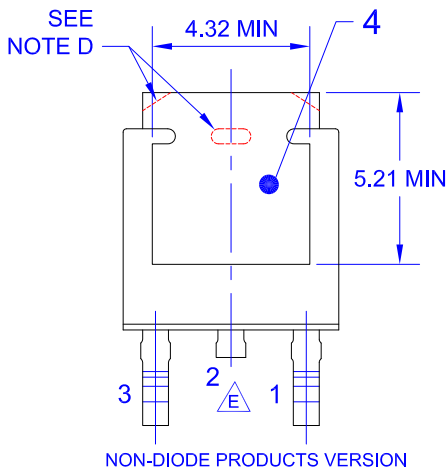
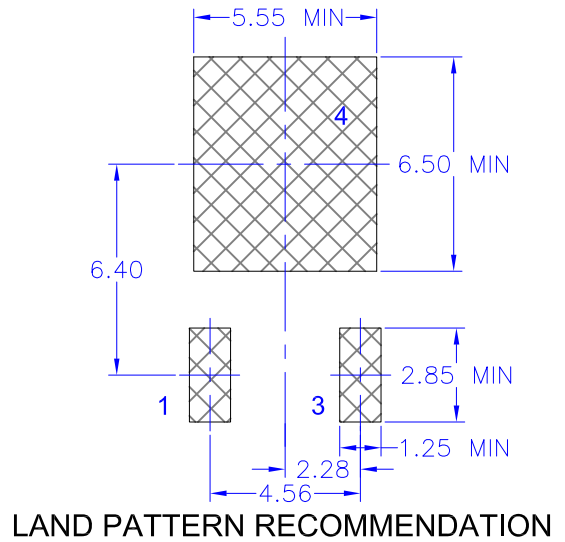
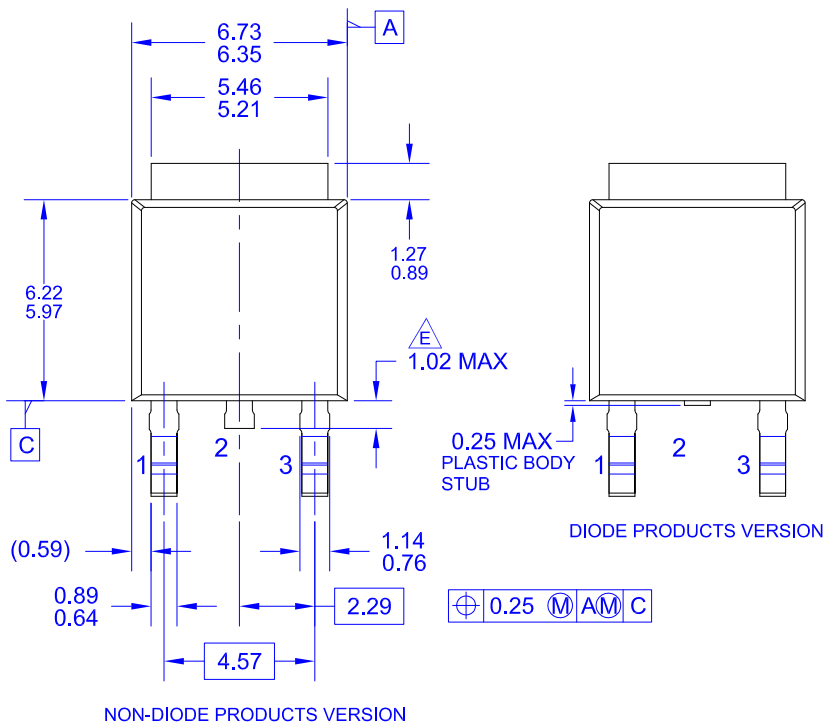


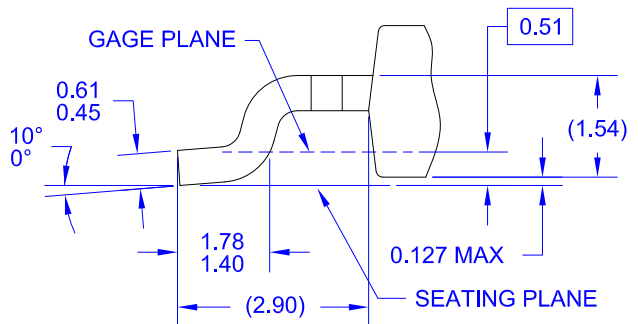
Figure 11. Transient Thermal Response Curve

Thermal characterization performed using the conditions described in Note 1b. Transient thermal response will change depending on the circuit board design.



NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE CONFORMS TO JEDEC, TO-252, ISSUE C, VARIATION AA.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.
- D) SUPPLIER DEPENDENT MOLD LOCKING HOLES OR CHAMFERED CORNERS OR EDGE PROTRUSION.
- E) TRIMMED CENTER LEAD IS PRESENT ONLY FOR DIODE PRODUCTS
- F) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.
- G) LAND PATTERN RECOMMENDATION IS BASED ON IPC7351A STD TO228P991X239-3N.
- H) DRAWING NUMBER AND REVISION: MKT-TO252A03REV10



DETAIL A  
(ROTATED -90°)  
SCALE: 12X







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